
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wang et al.

Attorney Docket No.: ALTRP100/A1198

Application No.: 10/719,218

Examiner: RAO, Shrinivas H.

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL AND DESIGN FOR ASSEMBLING A LOW-K Si DIE TO ACHIEVE AN INDUSTRIAL GRADE RELIABILITY WIRE BONDING PACKAGE Confirmation No.: 3208

CERTIFICATE OF EFS-WEB TRANSMISSION

I hereby certify that this correspondence is being transmitted electronically through EFS-WEB to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450 on August 29, 2007.

Signed: /Laura M. Dean/
Laura M. Dean

AMENDMENT E
FILED CONCURRENTLY WITH RCE

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the final Office Action mailed May 29, 2007, please consider the following remarks and amend the above-identified application as follows.

Amendments to the Claims are reflected in the listing of claims, which begin on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.